

VM171D

Preliminary Product Specification

General Description

The VM171D is a Microwave Monolithic Integrated Circuit (MMIC) designed in HEMT (High Electron Mobility Transistor) structure for operating frequency range from 32 to 36GHz.

The MMIC is developed on a 120nm GaN/SiC process and is internally matched for 50Ω RF accesses. It provides an output power of 43dBm, and associated power added efficiency of 28% in continuous wave (CW) or pulsed mode.

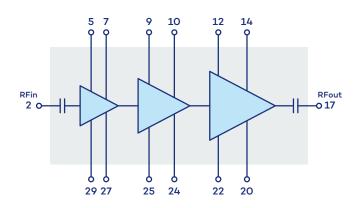
Features

Frequency range	32 – 36GHz
Output Power	43dBm @Pin = 26dBm
PAE	28% @Pin = 26dBm
Linear Gain	24dB
DC bias	$V_D = +24V$, $I_{DQ} = 640mA$ ($V_G = -2.1V$ Typical)
Chip size	4.5 x 4.5 x 0.1 (mm)

Applications

- Radar
- Satcom

Pins Assignement & Functional Block Diagram



Function	Pin number
RF in	2
V _{D1A} / V _{D1B}	7 / 27
V _{D2A} / V _{D2B}	10 / 24
VD3A / VD3B	14 / 20
V _{G1A} / V _{G1B}	5 / 29
VG2A / VG2B	9 / 25
Vg3A / Vg3B	12 / 22
RF out	17



• Electrical Specifications

Test conditions: unless otherwise noted

 \bullet T_{amb} = +25°C

• V_D = +24V

• I_{DQ} = 640mA (V_G = -2.1V Typ.)

Symbol	Parameter	Min	Тур	Max	Unit
F	Frequency range	32		36	GHz
G	Linear gain		24		dB
S11	Input return loss		-10		dB
S22	Output return loss		-10		dB
Pout	Output power (@Pin=26dBm)		43		dBm
PAE	Associated Power Added Efficiency (@Pin=26dBm)		28		%
lo	Associated Drain current (@Pin=26dBm)		4		Α
VD	Drain voltage		24		V

Recommended Operating Conditions

Symbol	Parameter	Value	Unit
VD	Drain voltage	24	V
IDQ	Drain quiescent current	640	mA
Vg	Gate voltage	-2.1 (Typ.)	V

Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
VD	Drain bias voltage	26	V
lo	Drain bias current	4.5	Α
Vg	Gate bias voltage	-1.8 to -2.2	V
Pin	Maximum peak input power overdrive	30	dBm
Tj	Junction temperature	225	°C
Та	Operating temperature range	-40/+85	°C
Tstg	Storage temperature range	-55/+150	°C

Operation of this device above any of these parameters may cause permanent damage.



Ordering information

Product Code	Parameter
VM171D	32 to 36GHz - 20W GaN/SiC Power Amplifier in die form

Associated Material

- Packaged die
- Die Evaluation Board (die EVB)
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- Mechanical files (DXF)
- Measurents files (S2P)

Product Compliance Information

Solderability

Use only AuSn (80/20) solder and limit exposure to temperature above 300 °C during 3-4 minutes, maximum.

ESD Sensitivy Rating

Test: Human Body Model (HBM) Std: JEDEC Standard JESD22-A114



RoHS-Compliance

This part is compliant with EU 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

Other attributes

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C15H12Br4O2) Free
- PFOS Free
- SVHC Free

Contact information

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about Vectrawave.

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Vectrawave Device

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